| ABSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>INDUSTRIES®<br>INTERNATIONAL AND | C, Bannockt   | ourn, Illinois. A         | ll rights reserved untions. | under both           | This docume<br>level parts, t | ent is a decla<br>he declaratio                                    | ration of th<br>n encompa | e substances<br>sses all lowe | within the n<br>er level mate | nanufacturer<br>rials for whi   | listed iten<br>ch the mar | n. Note: if<br>ufacturer       | the item is an as has engineering | sembly with lower<br>responsibility. |
|---|---|---------------------------|-----------------------------|----------------------|-------------------------------|--|---------------------------|-------------------------------|-------------------------------|---------------------------------|---------------------------|--------------------------------|-----------------------------------|--------------------------------------|
|   | IPC Web Site for Information on IPC-1752 Standard Form Type<br>http://www.ipc.org/IPC-175x Distribute |                           |                             |                      | e *                           | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Material |                           |                               |                               |                                 | ls and Mfg Information    |                                |                                   |                                      |
| Supplier Information  |   |                           |                             |                      |                               |  |                           |                               |                               |                                 |                           |                                |                                   |                                      |
| Company name*   | Company unique ID   |                           |                             | Unique ID Authority  |                               |  |                           |                               | Response Date*                |                                 |                           |                                |                                   |                                      |
| onsemi  |   |                           |                             |                      |                               |  |                           |                               |                               |                                 | 2023-06-08                |                                |                                   |                                      |
| Contact Name Title  |   |                           | Title - Contact             |                      |                               | Phone - Contact*   |                           |                               |                               | ]                               | Email - Contact*          |                                |                                   |                                      |
| Product-Env-Stewards  | Product Envi  | Product Enviro Compliance |                             |                      | NA                            |  |                           |                               |                               | Product-Env-Stewards@onsemi.com |                           |                                |                                   |                                      |
| Authorized Representative* Tit  |   |                           | Title - Representative      |                      |                               | Phone - Representative*  |                           |                               |                               | 1                               | Email - Representative*   |                                |                                   |                                      |
| Product-Env-Stewards  | Product Enviro Compliance   |                           |                             |                      | NA                            |  |                           |                               |                               | Product-Env-Stewards@onsemi.com |                           |                                |                                   |                                      |
| Requester Item Number   | Mfr Item Number   |                           | umber Mfr Item Name         |                      |                               | Effective Date Version Manufacturing Site                          |                           | ng Site                       | We                            | ight*                           | UOM                       | Unit Type                      |                                   |                                      |
|   | MM74H   | ММ74НС273МТС ОС           |                             | OCTAL D FLIP FLOP    |                               | 2023-06-08   |                           |                               | PH1                           |                                 | 69.                       | 28                             | mg                                | Each                                 |
| Manufacturing Proccess Information  | on  |                           |                             |                      |                               |  | 1                         |                               |                               |                                 | 1                         |                                |                                   | I                                    |
| Terminal Plating / Grid Array Mate  | rial T  | erminal Base              | Alloy                       | J-STD-020 MSL Rating |                               | Peak Process Body Temp   |                           | y Temperatu                   | ature Max Time at Peak Te     |                                 | emperature                | rature Number of Reflow Cycles |                                   | les                                  |
| Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)   |   | CU Alloy 1                |                             | 1                    |                               | 260  |                           | С                             | 30 seco                       |                                 | seconds                   | econds 3                       |                                   |                                      |
| Comments  |   |                           |                             |                      |                               |  |                           | ·                             | ·                             |                                 |                           |                                |                                   |                                      |
| evel 1 - maximum time at peak temperature   | e during so   | dering is 10-3            | 0 seconds                   |                      |                               |  |                           |                               |                               |                                 |                           |                                |                                   |                                      |
| for more information regarding material co  | mposition   | please refer to           | page 3                      |                      |                               |  |                           |                               |                               |                                 |                           |                                |                                   |                                      |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance               | CAS              | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|-------------------------|------------------|--------|--------|-----------------|
| Die                  | 0.29   | mg              | Supplier | Silicon (Si)            | 7440-21-3        |        | 0.29   | mg              |
| Die Attach           | 2.46   | mg              |          | Epoxy resin             | proprietary data |        | 0.246  | mg              |
|                      |        |                 | Supplier | Ethylene dimethacrylate | 97-90-5          |        | 0.123  | mg              |
|                      |        |                 | Supplier | Silver (Ag)             | 7440-22-4        |        | 1.968  | mg              |
|                      |        |                 | Supplier | Formaldehyde Polymer    | 9003-36-5        |        | 0.123  | mg              |
| Lead Frame           | 38.58  | mg              | Supplier | Iron (Fe)               | 7439-89-6        |        | 0.733  | mg              |
|                      |        |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 37.847 | mg              |
| Mold Compound-Black  | 24.35  | mg              |          | Epoxy resin             | proprietary data |        | 1.2175 | mg              |
|                      |        |                 | Supplier | Phenol Resin            | Proprietary Data |        | 0.974  | mg              |
|                      |        |                 | Supplier | Silica Amorphous (SiO2) | 7631-86-9        |        | 2.435  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)        | 1333-86-4        |        | 0.2435 | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)     | 60676-86-0       |        | 19.48  | mg              |
| Plating              | 3.44   | mg              | Supplier | Palladium (Pd)          | 7440-05-3        |        | 0.2614 | mg              |
|                      |        |                 | В        | Nickel (Ni)             | 7440-02-0        |        | 3.1304 | mg              |
|                      |        |                 | Supplier | Gold (Au)               | 7440-57-5        |        | 0.0482 | mg              |
| Wire Bond - Cu       | 0.16   | mg              | Supplier | Copper (Cu)             | 7440-50-8        |        | 0.16   | mg              |